

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJBD3020
Package Type :	PDFNWB3.3x3.3-8L-B

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	5.27%
Lead Frame	Copper	7440-50-8	97.342%	33.49%
	Iron	7439-89-6	2.40%	
	Zinc	7440-66-6	0.15%	
	Phosphorus	7723-14-0	0.10%	
	Lead (Pb)	7439-92-1	0.008%	
	Silver	7440-22-4	2.50%	
Die Attach	Lead	7439-92-1	83.45%	4.36%
	Tin	7440-31-5	4.50%	
	Silver	7440-22-4	2.15%	
	Butanediol mixture	107-88-0	8.50%	
	Modified castor oil	61788-85-0	1.40%	
Wire1	Copper	7440-50-8	99.996%	10.08%
	Others	/	0.004%	
Wire2	Copper	7440-50-8	97.95%	0.02%
	Palladium	7440/5/3	1.80%	
	Gold	7440-57-5	0.25%	
Mold Compound	Silica	60676-86-0	86.45%	46.26%
	Epoxy Resin	29690-82-2	6.50%	
	Phenol Resin	26834-02-6	6.50%	
	Carbon black	1333-86-4	0.55%	
Plating	Tin	7440-31-5	99.99%	0.52%
	Other	/	0.01%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.